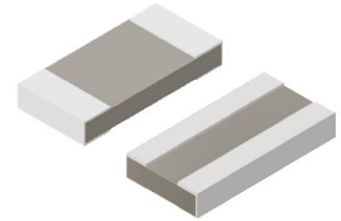


Features:

- Chip size from 0603 to 2512
- AlN substrate (thermal conductivity 170 W/mK)
- Low capacitance
- High insulation resistance between terminals
- RoHS compliant, REACH compliant, lead free, and halogen free



Electrical Specifications						
Type/Code	Thermal Resistance (°C/W), R _t	Thermal Conductance (mW/°C), G _t	Dielectric Withstanding Voltage kV _{AC} , RMS (60 Hz)	Operating Temperature Range (°C)	Storage Temperature Range (°C)	Substrate Material
TMJ0603C_0048	21	48	> 1.5	-55°C to +155°C	-55°C to +155°C	Aluminum nitride (170 W/mK)
TMJ0612G_0216	5	216				
TMJ1206G_0055	18	55				
TMJ1225G_0216	5	216				
TMJ2512G_0053	19	53				

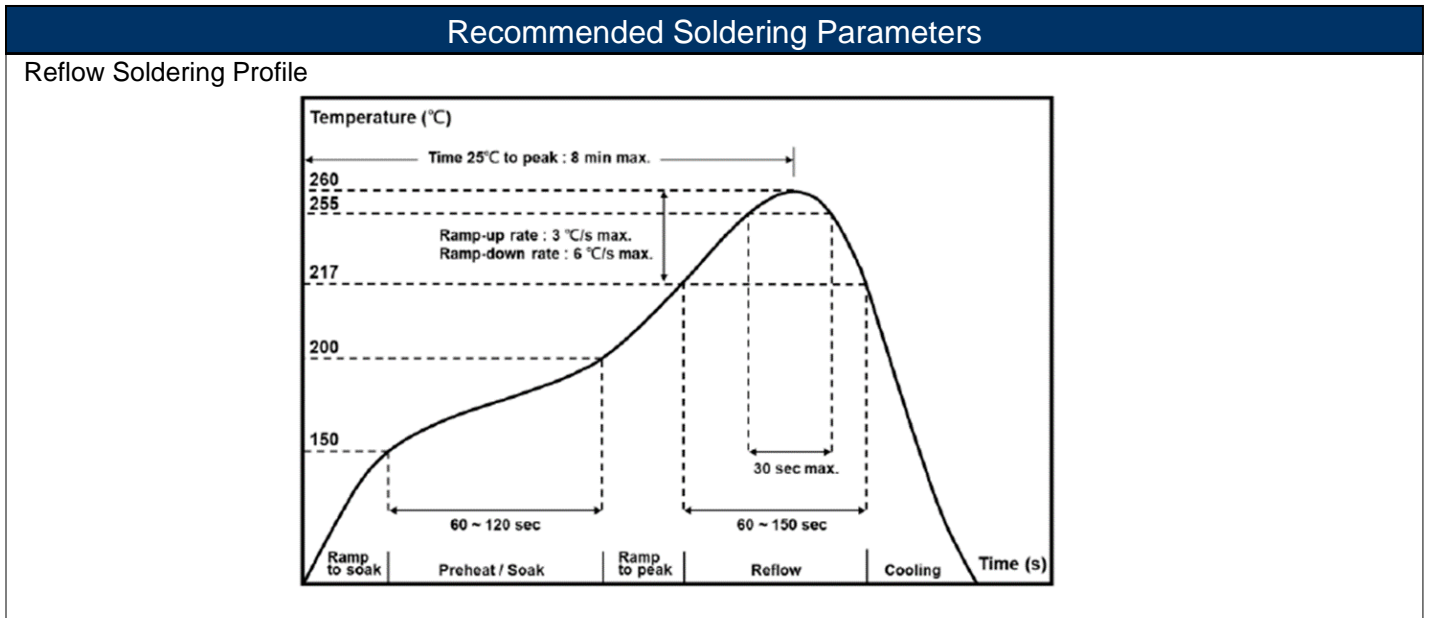
Note: $R_t = \frac{L}{k(H*W)}$; $G_t = 1/R_t$

k = 170 W/mK (the thermal conductivity of AlN)

Construction Diagram															
	<table border="1"> <thead> <tr> <th>Reference</th> <th>Description</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>Aluminum Nitride Substrate</td> </tr> <tr> <td>2</td> <td>Top Inner Electrode</td> </tr> <tr> <td>3</td> <td>Bottom Inner Electrode</td> </tr> <tr> <td>4</td> <td>Side Inner Electrode</td> </tr> <tr> <td>5</td> <td>Nickel Barrier</td> </tr> <tr> <td>6</td> <td>Solder Coating (Sn)</td> </tr> </tbody> </table>	Reference	Description	1	Aluminum Nitride Substrate	2	Top Inner Electrode	3	Bottom Inner Electrode	4	Side Inner Electrode	5	Nickel Barrier	6	Solder Coating (Sn)
	Reference	Description													
	1	Aluminum Nitride Substrate													
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	3	Bottom Inner Electrode													
	4	Side Inner Electrode													
	5	Nickel Barrier													
6	Solder Coating (Sn)														

Mechanical Specifications					
Type/Code	L	W	H	i	Unit
TMJ0603C_0048	0.063 ± 0.005	0.031 ± 0.005	0.022 ± 0.005	0.016 ± 0.005	inches
	1.60 ± 0.13	0.80 ± 0.13	0.55 ± 0.13	0.40 ± 0.13	mm
TMJ0612G_0216	0.063 ± 0.005	0.126 ± 0.005	0.028 ± 0.005	0.016 ± 0.005	inches
	1.60 ± 0.13	3.20 ± 0.13	0.70 ± 0.13	0.40 ± 0.13	mm
TMJ1206G_0055	0.126 ± 0.005	0.063 ± 0.005	0.028 ± 0.005	0.020 ± 0.005	inches
	3.20 ± 0.13	1.60 ± 0.13	0.70 ± 0.13	0.50 ± 0.13	mm
TMJ1225G_0216	0.126 ± 0.005	0.252 ± 0.005	0.028 ± 0.005	0.024 ± 0.005	inches
	3.20 ± 0.13	6.40 ± 0.13	0.70 ± 0.13	0.60 ± 0.13	mm
TMJ2512G_0053	0.252 ± 0.005	0.126 ± 0.005	0.028 ± 0.005	0.024 ± 0.005	inches
	6.40 ± 0.13	3.20 ± 0.13	0.70 ± 0.13	0.60 ± 0.13	mm

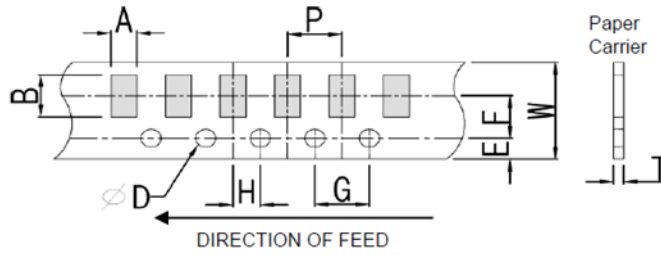
Performance Characteristics			
Test	Test Method	Test Condition	Test Specification
Solderability	JIS-C-5201-1 4.17 IEC-60115-1 4.17	245 ± 5°C for 3 seconds	>95% coverage No visual damage
Solder Mounting Integrity	MIL-PRF-55342 method par. 4.8.13.1	For size 0603 applied 9.8N Sizes 0612 and above applied 19.6N for 60 ± 1 seconds	No visual damage
Bending Strength	JIS-C-5201-1 4.33 IEC-60115-1 4.33	Bending once for 5 seconds D: 0603 = 5mm 1206 - 0613 = 3mm 2512 - 1225 = 2mm	No visual damage



Packaging Specifications

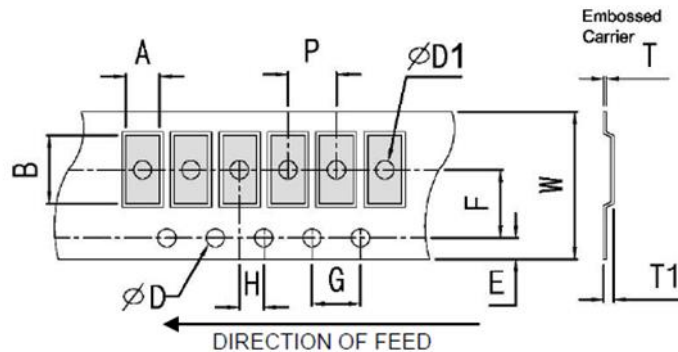
Size	A	ØB	ØC	ØD	W	ØM	Unit
0603, 0612, 1206	0.079 ± 0.020	0.531 ± 0.039	0.827 ± 0.039	2.362 ± 0.039	0.453 ± 0.079	7.008 ± 0.079	inches
	2.00 ± 0.50	13.50 ± 1.00	21.00 ± 1.00	60.00 ± 1.00	11.50 ± 2.00	178.00 ± 2.00	mm
2512, 1225	0.079 ± 0.020	0.531 ± 0.039	0.827 ± 0.039	2.362 ± 0.039	0.630 ± 0.079	7.008 ± 0.079	inches
	2.00 ± 0.50	13.50 ± 1.00	21.00 ± 1.00	60.00 ± 1.00	16.00 ± 2.00	178.00 ± 2.00	mm

Taping Specifications – Paper Tape



Size	A	B	W	E	F	Unit
0603	0.041 ± 0.008	0.071 ± 0.008	0.315 ± 0.008	0.069 ± 0.004	0.138 ± 0.002	inches
	1.05 ± 0.20	1.80 ± 0.20				mm
0612	0.112 ± 0.008	0.120 ± 0.008	8.00 ± 0.20	1.75 ± 0.10	3.50 ± 0.05	inches
	2.85 ± 0.20	3.05 ± 0.20				mm
1206	0.075 ± 0.008	0.138 ± 0.008				inches
	1.90 ± 0.20	3.50 ± 0.20				mm
Type/Code	G	H	T	ØD	P	Unit
0603	0.157 ± 0.004	0.079 ± 0.002	0.024 ± 0.004	0.059 +0.004/-0.00	0.157 ± 0.004	inches
			0.60 ± 0.10			mm
0612	4.00 ± 0.10	2.00 ± 0.05	0.030 ± 0.004	1.50 +0.10/-0.00	4.00 ± 0.10	inches
			0.75 ± 0.10			mm
1206			0.030 ± 0.004			inches
			0.75 ± 0.10			mm

Taping Specifications – Embossed Plastic Tape



Size	A	B	W	E	F	G	Unit
1225, 2512	0.134 ± 0.008	0.264 ± 0.008	0.472 ± 0.004	0.069 ± 0.004	0.217 ± 0.020	0.157 ± 0.004	inches
	3.40 ± 0.20	6.70 ± 0.20	12.00 ± 0.10	1.75 ± 0.10	5.50 ± 0.50	4.00 ± 0.10	mm
	H	T	ØD	ØD1	T1	P	Unit
1225, 2512	0.079 ± 0.002	0.009 ± 0.004	0.059 +0.004/-0.00	0.059 ± 0.004	0.033 ± 0.006	0.157 ± 0.004	inches
	2.00 ± 0.05	0.23 ± 0.10	1.50 +0.10/-0.00	1.50 ± 0.10	0.85 ± 0.15	4.00 ± 0.10	mm

RoHS Compliance

Stackpole Electronics has joined the worldwide effort to reduce the amount of lead in electronic components and to meet the various regulatory requirements now prevalent, such as the European Union’s directive regarding “Restrictions on Hazardous Substances” (RoHS 3). As part of this ongoing program, we periodically update this document with the status regarding the availability of our compliant components. All our standard part numbers are compliant to EU Directive 2011/65/EU of the European Parliament as amended by Directive (EU) 2015/863/EU as regards the list of restricted substances.

RoHS Compliance Status						
Standard Product Series	Description	Package / Termination Type	Standard Series RoHS Compliant	Lead-Free Termination Composition	Lead-Free Mfg. Effective Date (Std Product Series)	Lead-Free Effective Date Code (YY/WW)
TMJ	Thermal SMD Jumper	SMD	YES	100% Matte Sn over Ni	Always	Always

“Conflict Metals” Commitment

We at Stackpole Electronics, Inc. are joined with our industry in opposing the use of metals mined in the “conflict region” of the eastern Democratic Republic of the Congo (DRC) in our products. Recognizing that the supply chain for metals used in the electronics industry is very complex, we work closely with our own suppliers to verify to the extent possible that the materials and products we supply do not contain metals sourced from this conflict region. As such, we are in compliance with the requirements of Dodd-Frank Act regarding Conflict Minerals.

Compliance to “REACH”

We certify that all passive components supplied by Stackpole Electronics, Inc. are SVHC (Substances of Very High Concern) free and compliant with the requirements of EU Directive 1907/2006/EC, “The Registration, Evaluation, Authorization and Restriction of Chemicals”, otherwise referred to as REACH. Contact us for complete list of REACH Substance Candidate List.

Environmental Policy

It is the policy of Stackpole Electronics, Inc. (SEI) to protect the environment in all localities in which we operate. We continually strive to improve our effect on the environment. We observe all applicable laws and regulations regarding the protection of our environment and all requests related to the environment to which we have agreed. We are committed to the prevention of all forms of pollution.

How to Order

